

Ankit Kaul

List of Publications by Year in descending order

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22
citing authors

#	ARTICLE	IF	CITATIONS
1	BEOL-Embedded 3D Polylithic Integration: Thermal and Interconnection Considerations. , 2020, , .		12
2	Microfluidic Cooling of a 14-nm 2.5-D FPGA With 3-D Printed Manifolds for High-Density Computing: Design Considerations, Fabrication, and Electrical Characterization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2393-2403.	2.5	8
3	Monolithic Microfluidic Cooling of a Heterogeneous 2.5-D FPGA With Low-Profile 3-D Printed Manifolds. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 974-982.	2.5	6
4	Benchmarking Monolithic 3D Integration for Compute-in-Memory Accelerators: Overcoming ADC Bottlenecks and Maintaining Scalability to 7nm or Beyond. , 2020, , .		6
5	A Compute-in-Memory Hardware Accelerator Design With Back-End-of-Line (BEOL) Transistor Based Reconfigurable Interconnect. IEEE Journal on Emerging and Selected Topics in Circuits and Systems, 2022, 12, 445-457.	3.6	5
6	Thermal Modeling of 3D Polylithic Integration and Implications on BEOL RRAM Performance. , 2020, , .		4
7	Thermal Reliability Considerations of Resistive Synaptic Devices for 3D CIM System Performance. , 2021, , .		4
8	Design Considerations, Demonstration, and Benchmarking of Silicon Microcold Plate and Monolithic Microfluidic Cooling for 2.5D ICs. , 2021, , .		3
9	Multilevel Signaling for High-Speed Chiplet-to-Chiplet Communication. IFIP Advances in Information and Communication Technology, 2021, , 149-178.	0.7	1
10	Modeling and simulation of an HVAC system for energy analysis and management of commercial buildings. , 2014, , .		0
11	Electrical and Performance Benefits of Advanced Monolithic Cooling for 2.5D Heterogeneous ICs. , 2021, , .		0